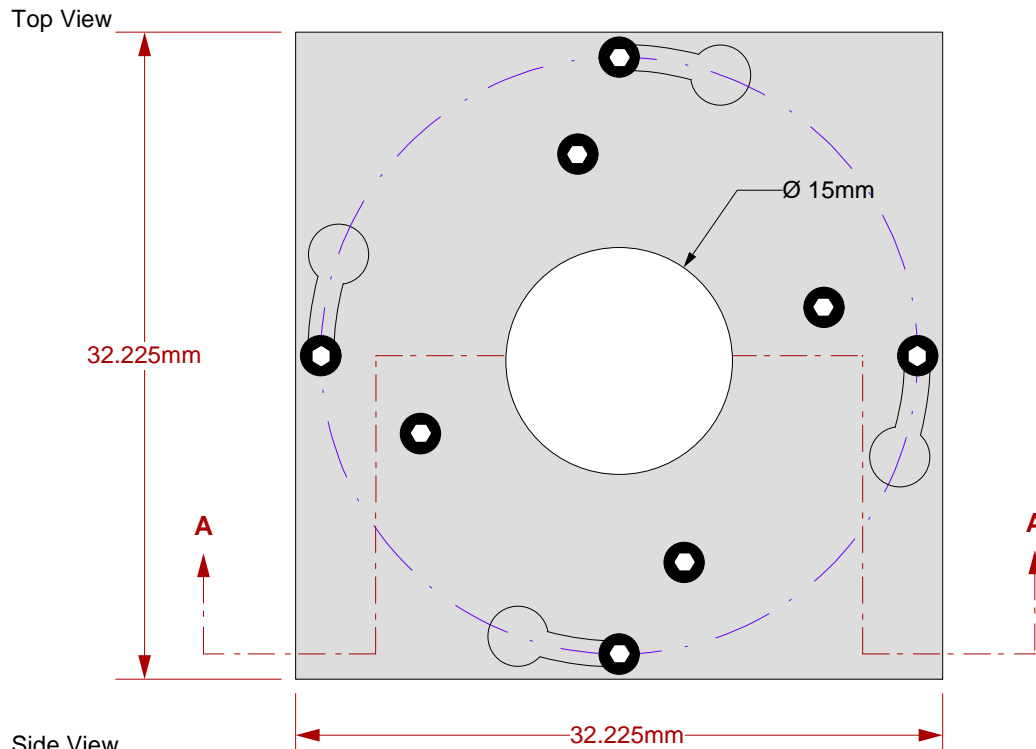
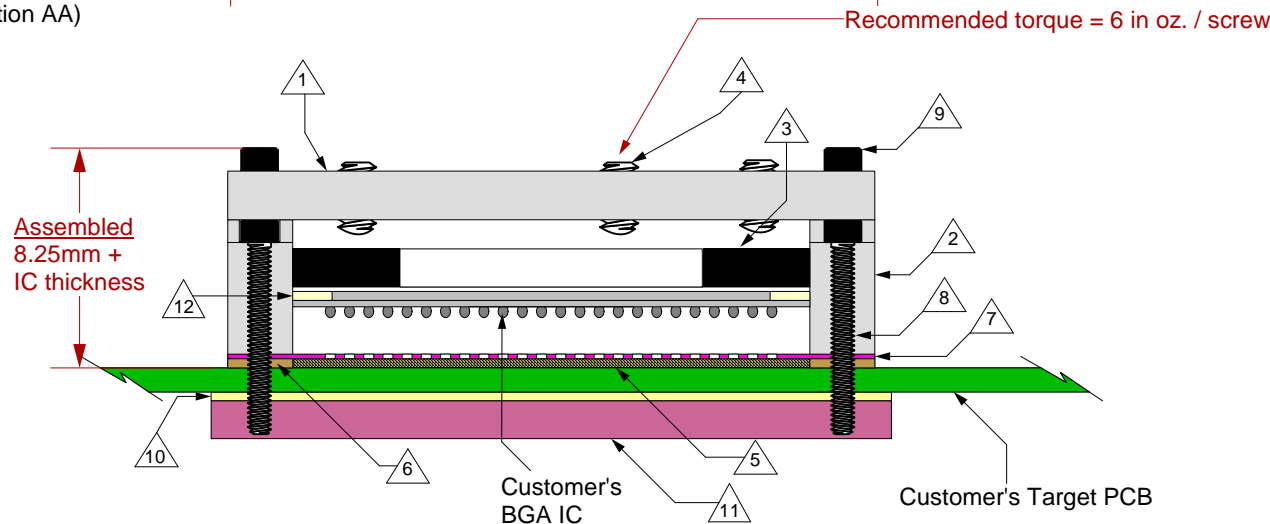


GHz BGA Socket - Direct mount, solderless



Side View
(Section AA)



Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid

- △ 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- △ 2 Socket base: Black anodized Aluminum. Thickness = 5mm.
- △ 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- △ 4 Compression screw: Black anodized Aluminum. 3-48 thread (x4)
- △ 5 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- △ 6 Elastomer Guide: Non-clad FR4. Thickness = 0.725mm.
- △ 7 Ball Guide: Kapton polyimide.
- △ 8 Socket base screw: Cap head, Alloy steel with black oxide finish, 0-80 fine thread, 12.7mm long.
- △ 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- △ 10 Insulation Plate: FR4/G10, 1.59mm thick.
- △ 11 Backing Plate: Anodized Aluminum 6.35mm thick.
- △ 12 IC Frame: Ultem

SG-BGA-6299 Drawing

Status: Released

Scale: -

Rev: A

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Drawing: E Smolentseva

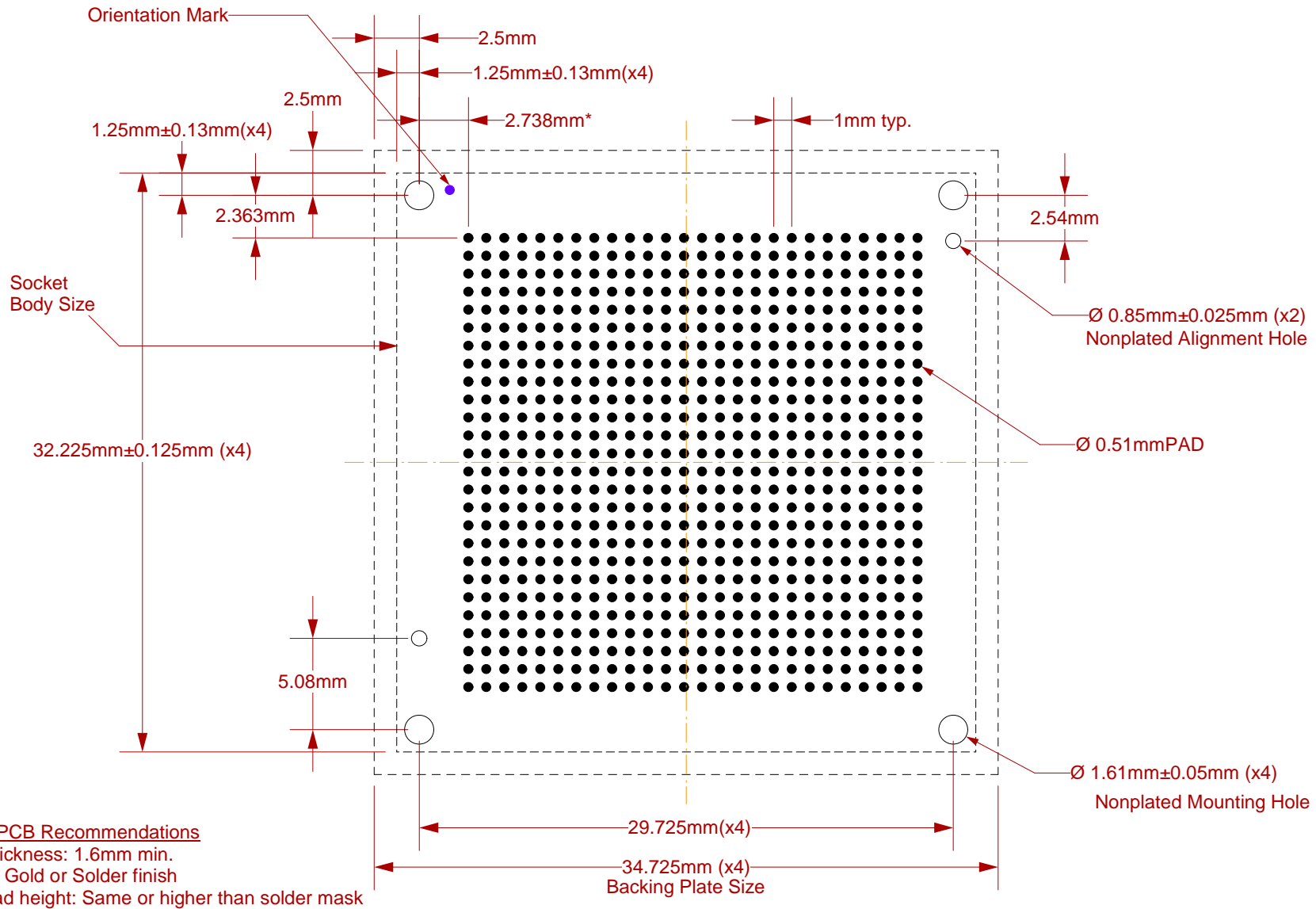
Date: 2/16/10

File: SG-BGA-6299 Dwg

Modified:

All tolerances: $\pm 0.125\text{mm}$ (unless stated otherwise). Materials and specifications are subject to change without notice.


***Note: BGA pattern is shifted to the right by 0.375mm in respect to the mounting holes**

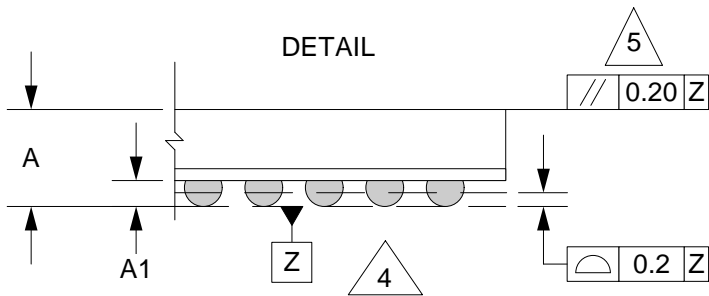
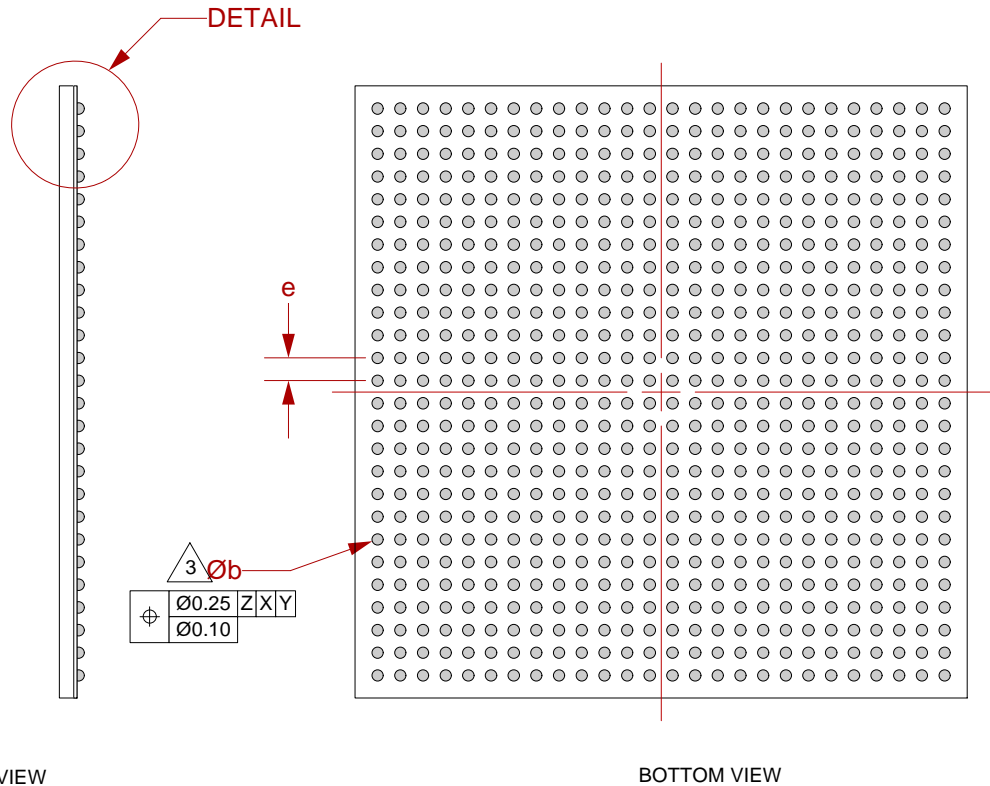
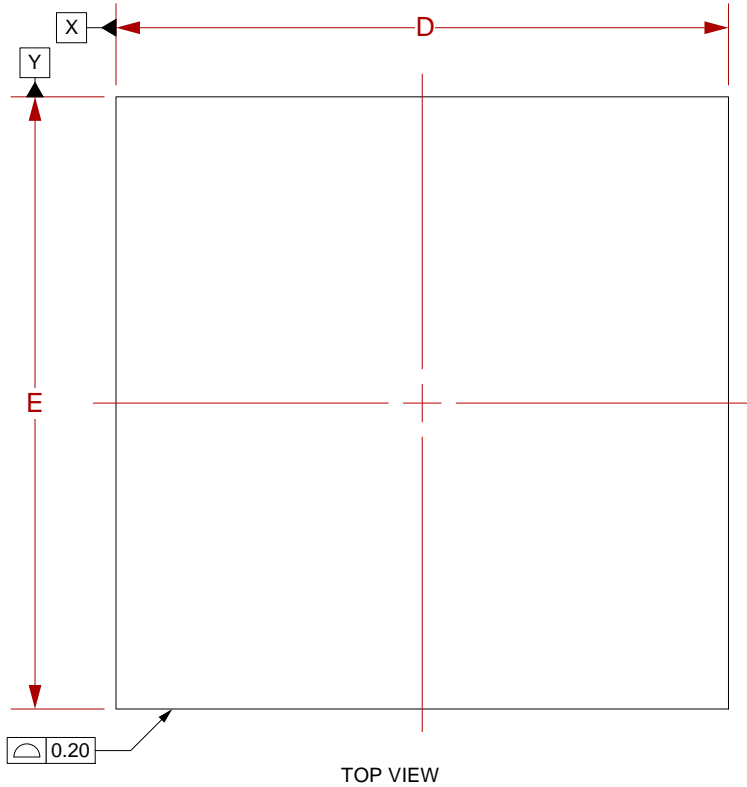


Target PCB Recommendations
 Total thickness: 1.6mm min.
 Plating: Gold or Solder finish
 PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.


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	<p>Drawing: E Smolentseva</p>	<p>Date: 2/16/10</p>		
	<p>File: SG-BGA-6299 Dwg</p>	<p>Modified:</p>		

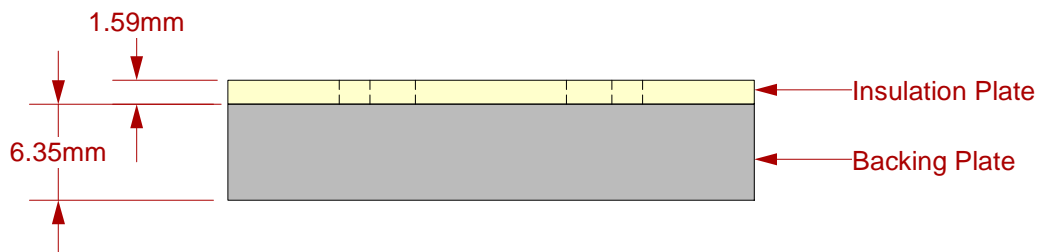
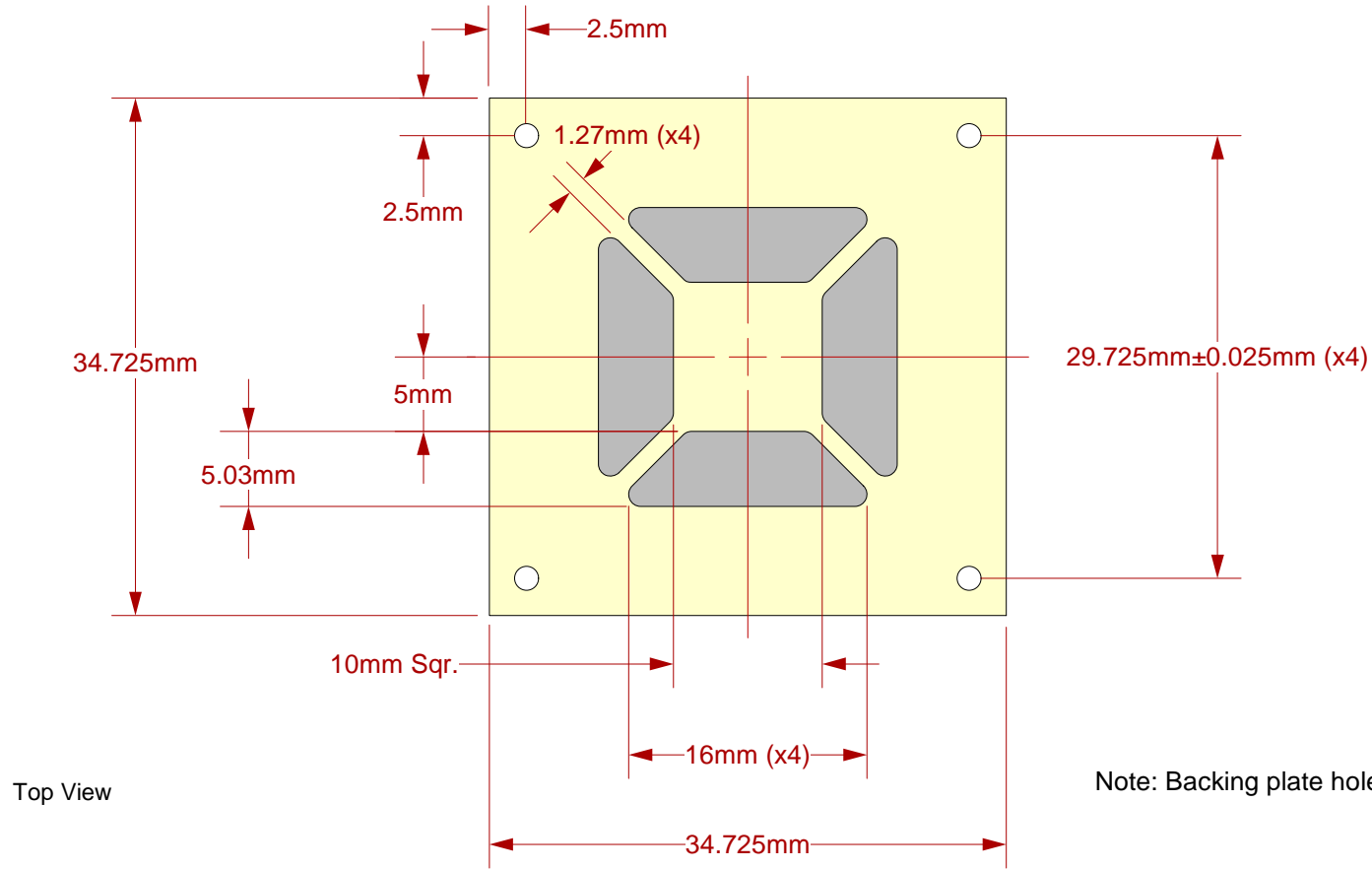


- 1 Dimensions are in millimeters.
- 2 Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3 Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- 4 Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- 5 Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.5
A1	0.4	0.6
b		0.70
D	27.00 BSC	
E	27.00 BSC	
e	1.0 BSC	


Array 26x26

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	File: SG-BGA-6299 Dwg		Modified:	



Description: Backing Plate with Insulation Plate

All dimensions are in mm.
All tolerances are +/- 0.125mm.
(Unless stated otherwise)

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		File: SG-BGA-6299 Dwg	Modified:	